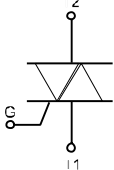


	Description	4A TRIACs												
  DPAK	Planar passivated high commutation three Quadrant triac in a (DPAK) surface-mountable plastic package. This "series B " triac balances the requirements of commutation performance and gate sensitivity and is intended for interfacing with low power drivers and logic ICs including microcontrollers.													
MAIN FEATURES <table border="1" data-bbox="212 808 748 997"> <thead> <tr> <th>Symbol</th><th>Value</th><th>Unit</th></tr> </thead> <tbody> <tr> <td>$I_{T(RMS)}$</td><td>4</td><td>A</td></tr> <tr> <td>V_{DRM}/V_{RRM}</td><td>800</td><td>V</td></tr> <tr> <td>$I_{G(QI)}$</td><td>10</td><td>mA</td></tr> </tbody> </table>			Symbol	Value	Unit	$I_{T(RMS)}$	4	A	V_{DRM}/V_{RRM}	800	V	$I_{G(QI)}$	10	mA
Symbol	Value	Unit												
$I_{T(RMS)}$	4	A												
V_{DRM}/V_{RRM}	800	V												
$I_{G(QI)}$	10	mA												

Absolute Maximum Rating				
Symbol	Parameter	Conditions	Value	Unit
V_{DRM}	repetitive peak off-state voltage		800	V
I_{TSM}	non-repetitive peak on-state current	full sine wave; $T_j(\text{init}) = 25^\circ\text{C}$; $t_p = 20\text{ ms}$; (see Fig.4, Fig.5)	25	A
		full sine wave; $T_j(\text{init}) = 25^\circ\text{C}$; $t_p = 16.7\text{ ms}$	27	A
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 107^\circ\text{C}$ (see Fig.1, Fig.2, Fig.3)	4	A
I^2t	I^2t for fusing	$t_p = 10\text{ ms}$; sine-wave pulse	3.1	A^2s
dI_T/dt	rate of rise of on-state current	$I_T = 6\text{ A}$; $I_G = 0.2\text{ A}$; $dI_G/dt = 0.2\text{ A}/\mu\text{s}$;	100	$\text{A}/\mu\text{s}$
I_{GM}	peak gate current		2	A
P_{GM}	peak gate power		5	W
$P_{G(AV)}$	average gate power	over any 20 ms period	0.5	W
T_{stg}	storage temperature		-40~+150	$^\circ\text{C}$
T_j	junction temperature		125	$^\circ\text{C}$

Static Characteristics ($T_j = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{GT}	Gate trigger current	$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2+ \text{ G+}$ (see Fig.7)	-	-	10	mA
		$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2+ \text{ G-}$ (see Fig.7)	-	-	10	mA
		$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2- \text{ G-}$ (see Fig.7)	-	-	10	mA
I_L	latching current	$V_D = 12\text{ V}; I_G = 0.1\text{ A}; T_2+ \text{ G+}$ (see Fig.8)	-	-	12	mA
		$V_D = 12\text{ V}; I_G = 0.1\text{ A}; T_2+ \text{ G-}$ (see Fig.8)	-	-	18	mA
		$V_D = 12\text{ V}; I_G = 0.1\text{ A}; T_2- \text{ G-}$ (see Fig.8)	-	-	12	mA
I_H	holding current	$V_D = 12\text{ V};$ (see Fig.9)	-	-	12	mA
V_T	on-state voltage	$I_T = 5\text{ A};$ (see Fig.10)	-	1.4	1.7	V
V_{GT}	gate trigger voltage	$V_D = 12\text{ V}; I_T = 0.1\text{ A}$ (See Fig.11)	-	0.7	1.5	V
		$V_D = 400\text{ V}; I_T = 0.1\text{ A}; T_j = 125^\circ\text{C}$ (see Fig.11)	0.25	0.4	-	V
I_D	off-state current	$V_D = 800\text{ V}; T_j = 125^\circ\text{C}$	-	0.1	0.5	mA

Dynamic Characteristics ($T_j = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
dV_D/dt	rate of rise of off-state voltage	$V_{DM} = 536\text{ V}; T_j = 125^\circ\text{C}$ exponential waveform; gate open circuit	30			V/ μs
dI_{com}/dt	rate of change of commutating current	$V_D = 400\text{ V}; T_j = 125^\circ\text{C}; I_{T(RMS)} = 4\text{ A};$ $dV_{com}/dt = 0.1\text{ V}/\mu\text{s};$ gate open circuit	8			A/ms
		$V_D = 400\text{ V}; T_j = 125^\circ\text{C}; I_{T(RMS)} = 4\text{ A};$ $dV_{com}/dt = 10\text{ V}/\mu\text{s};$ gate open circuit	2.1			A/ms
t_{gt}	gate-controlled turn-on time	$I_{TM} = 6\text{ A}; V_D = 600\text{ V}; I_G = 0.1\text{ A};$ $dI_G/dt = 5\text{ A}/\mu\text{s}$		2		μs

Thermal Resistances

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-L)}$	thermal resistance from junction to mounting base	half cycle (see Fig.6)			3.7	K/W
		full cycle (see Fig.6)			3	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air; printed circuit board (FR4) mounted		75		K/W

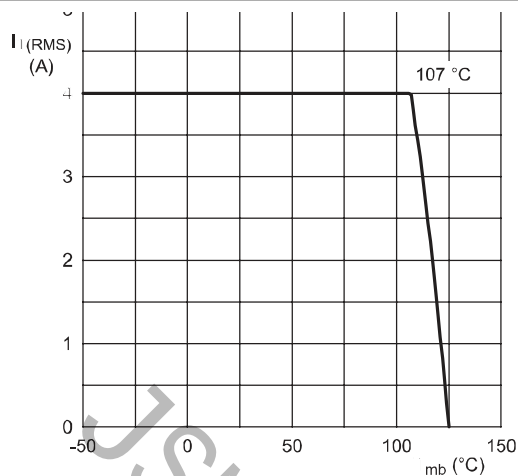


Fig 1. RMS on-state current as a function of mounting base temperature; maximum values

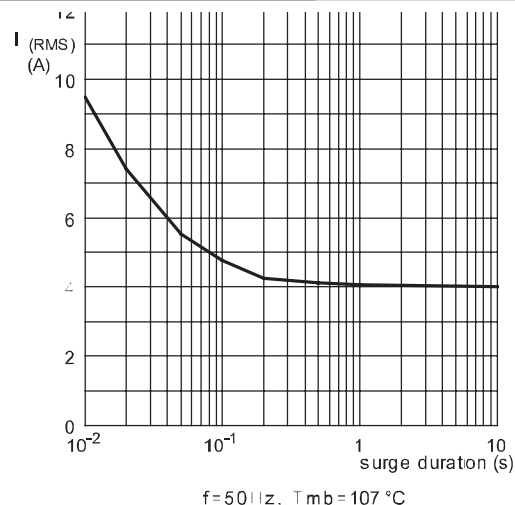


Fig 2. RMS on-state current as a function of surge duration; maximum values

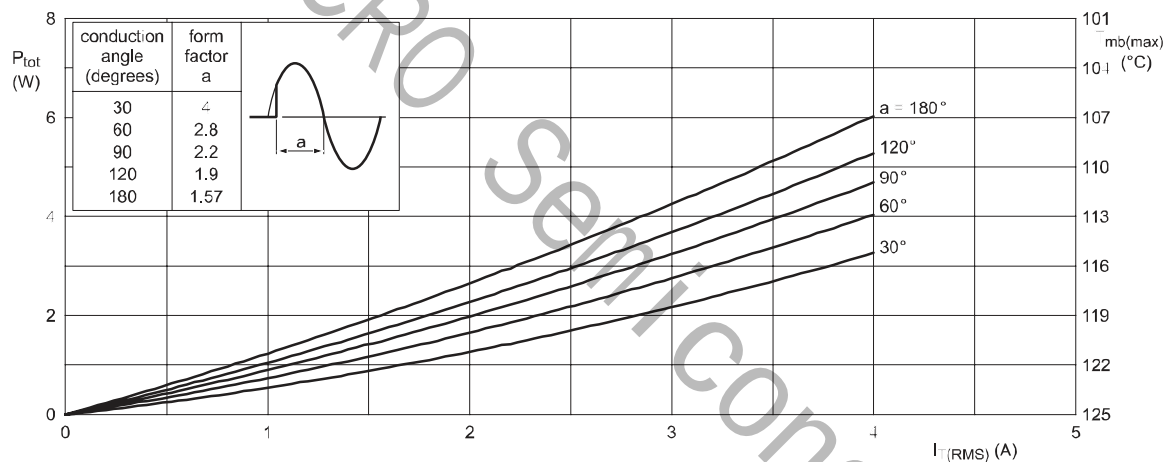
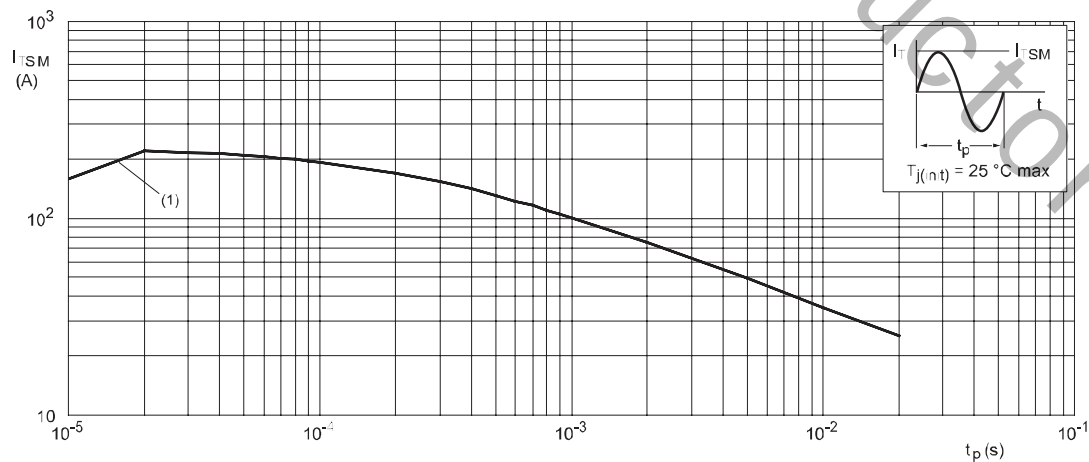


Fig 3. Total power dissipation as a function of RMS on-state current; maximum values



$t_p \leq 20 \text{ ms}; (1) dI_T/dt \text{ limit}$

Fig 4. Non-repetitive peak on-state current as a function of pulse width; maximum values

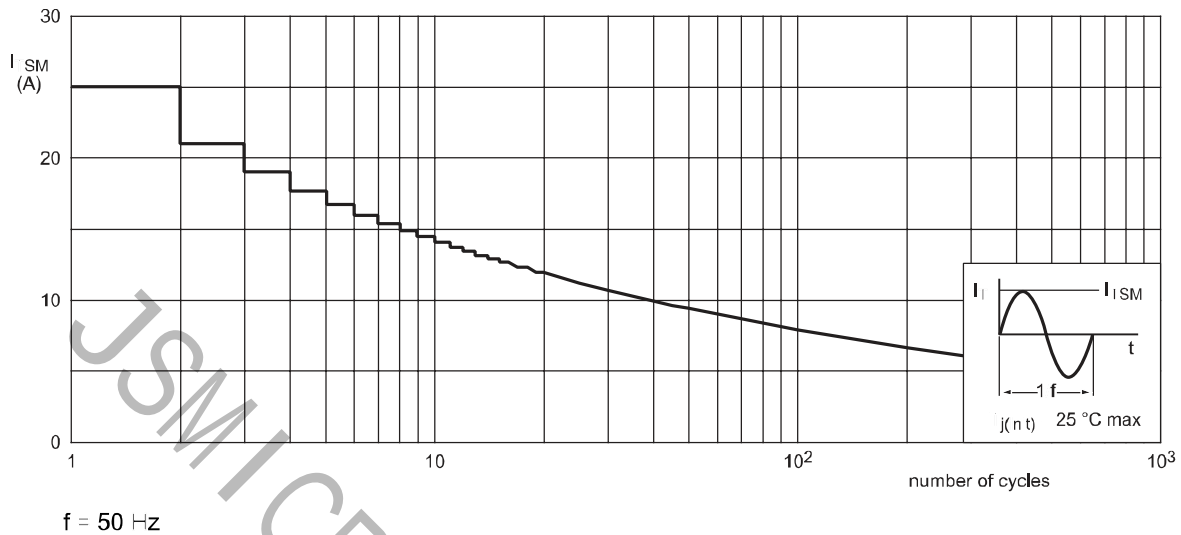
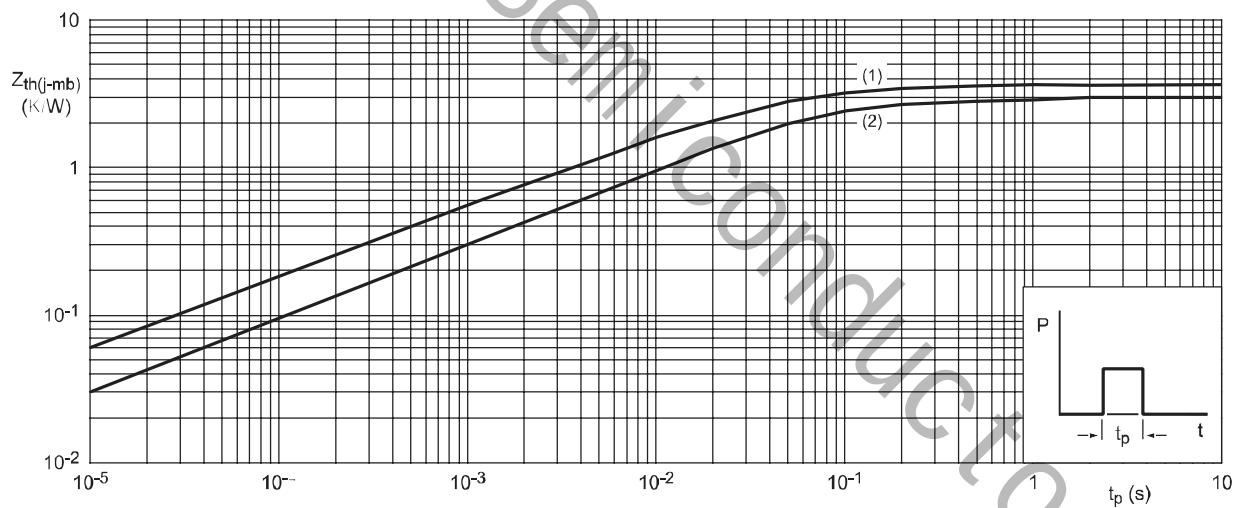
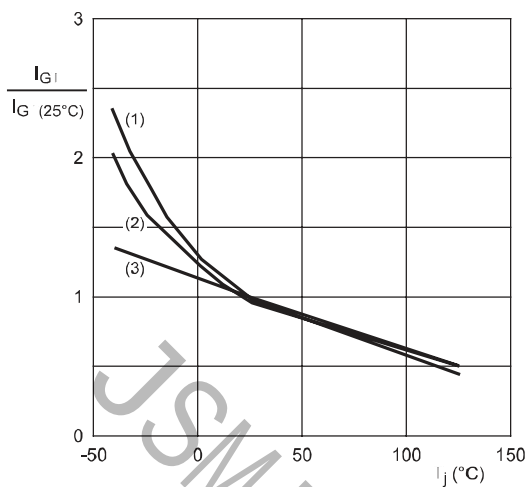


Fig 5. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



- (1) Unidirectional (half cycle)
- (2) Bidirectional (full cycle)

Fig 6. Transient thermal impedance from junction to mounting base as a function of pulse width



- (1) T2- G-
(2) T2+ G-
(3) T2+ G+

Fig 7. Normalized gate trigger current as a function of junction temperature

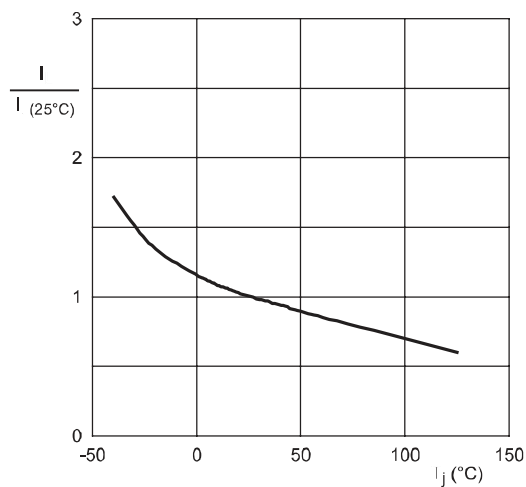


Fig 8. Normalized latching current as a function of junction temperature

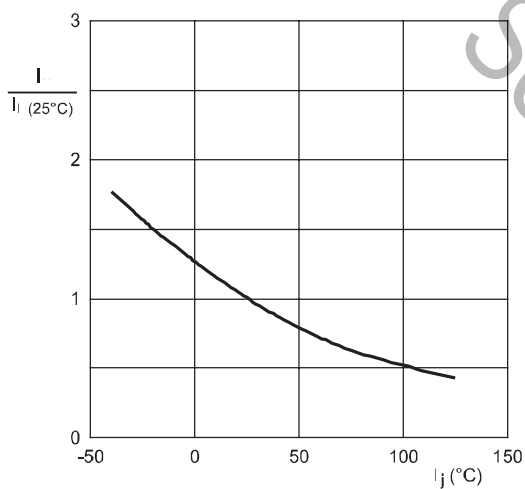
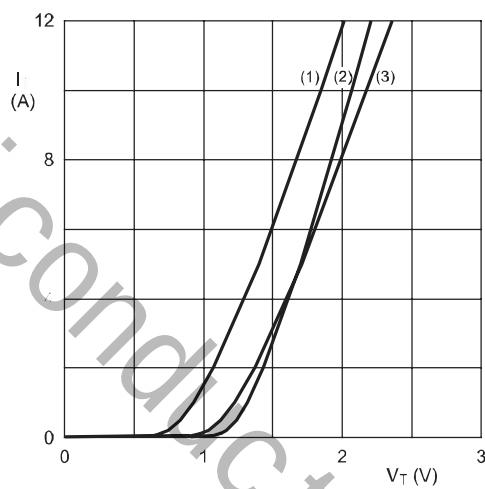


Fig 9. Normalized holding current as a function of junction temperature



$V_o = 1.27 \text{ V}$; $R_s = 0.091 \Omega$

- (1) $T_j = 125^\circ\text{C}$; typical values
(2) $T_j = 125^\circ\text{C}$; maximum values
(3) $T_j = 25^\circ\text{C}$; maximum values

Fig 10. On-state current as a function of on-state voltage

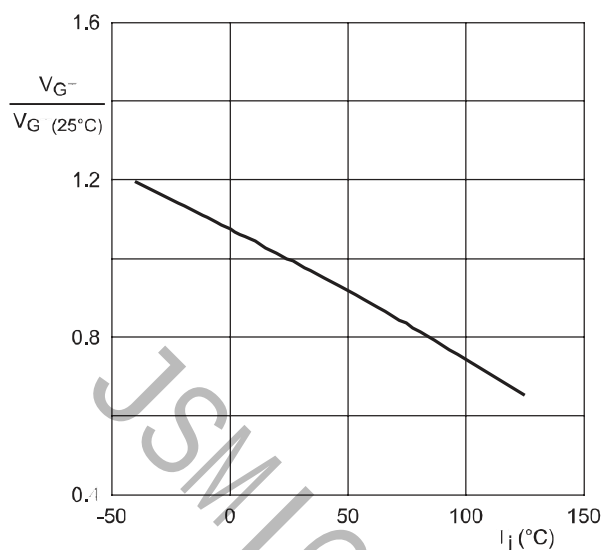
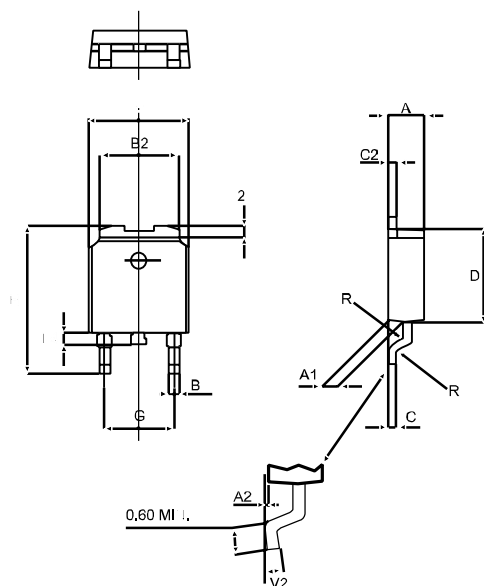


Fig 11. Normalized gate trigger voltage as a function of junction temperature

PACKAGE MECHANICAL DATA

DPAK (Plastic)



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max	Min.	Max.
A	2.20	2.40	0.086	0.094
A1	0.90	1.10	0.035	0.043
A2	0.03	0.23	0.001	0.009
B	0.64	0.90	0.025	0.035
B2	5.20	5.40	0.204	0.212
C	0.45	0.60	0.017	0.023
C2	0.48	0.60	0.018	0.023
D	6.00	6.20	0.236	0.244
E	6.40	6.60	0.251	0.259
G	4.40	4.60	0.173	0.181
H	9.35	10.10	0.368	0.397
L2	0.80 typ.		0.031 typ.	
L4	0.60	1.00	0.023	0.039
R	0.2 typ.		0.007 typ.	
V2	0°	8°	0°	8°